

REV.	DATE	DCN NO.	DESCRIPTION	DR.	CHK.	APPD.	APPD.
2	10.Feb.2006	059307	CORRECTION OF ERROR IN WRITTING	E.MURANO	Y.YAHIRO		K.HIYAMA

DESIGNATION

MM50-200B*-B1

SERIES PREFIX
シリーズ名
NO. OF CONTACTS
芯数

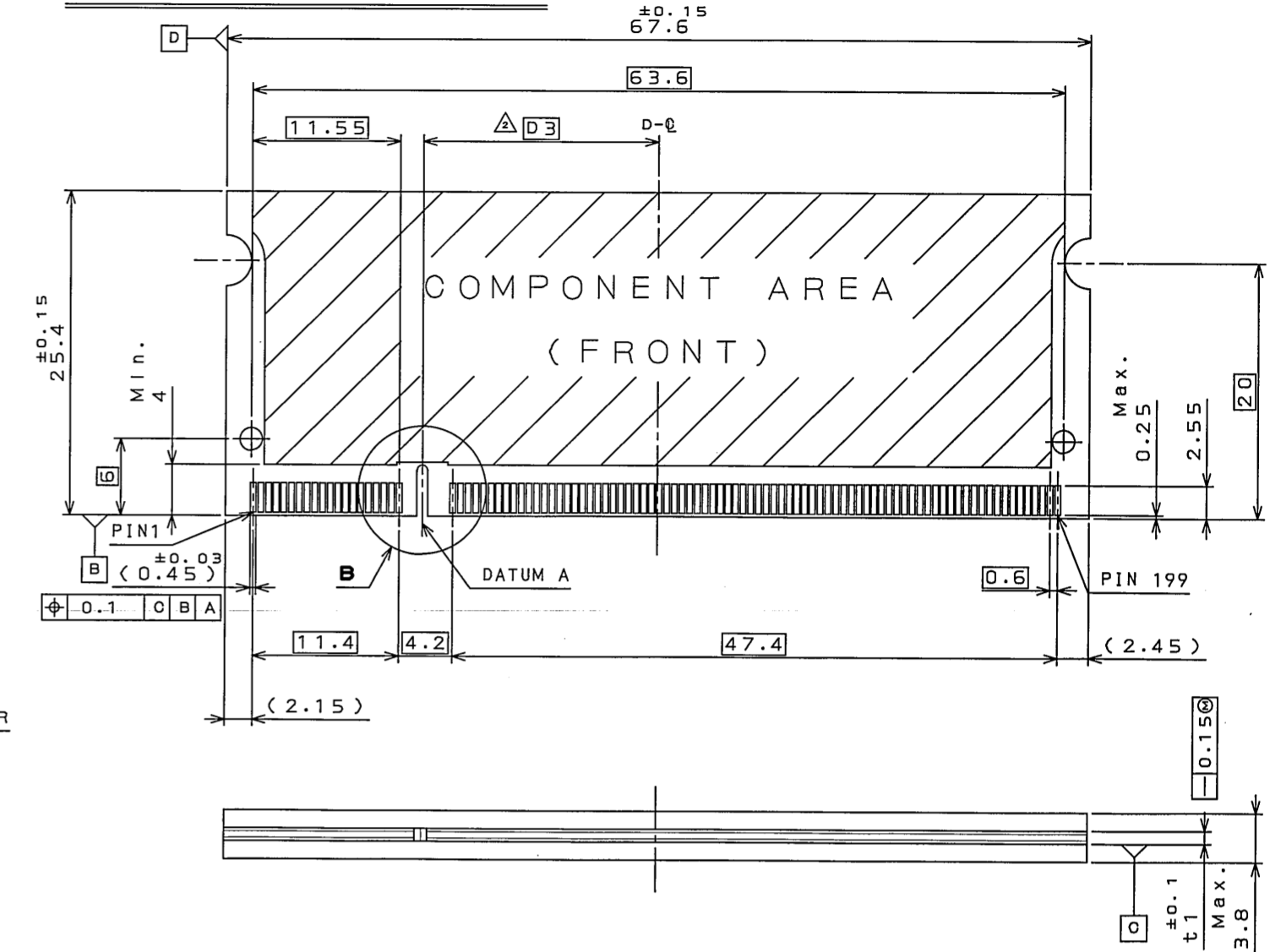
CONTACT FINISH
接点仕上げ
1:Au(0.1µm MIN) OVER NI

MODIFY CODE
モディファイコード
B:4.0mm HIGHT

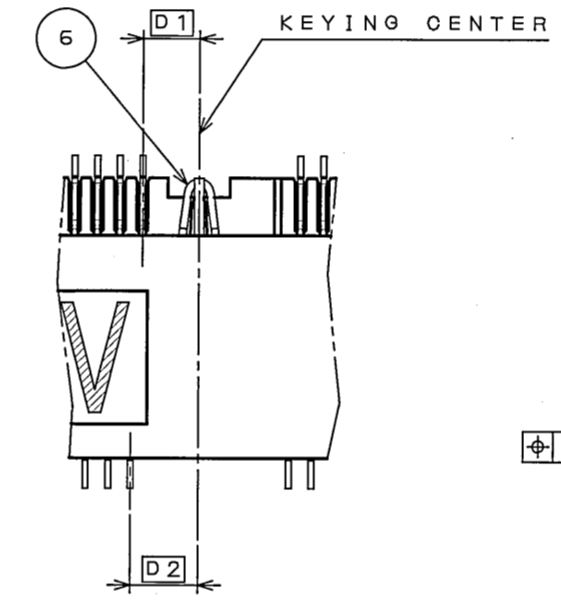
SOCKET TYPE
ソケットタイプ
B:LATCH TYPE SMT

KEYING TYPE(Detail A)
キタイプ
2:TYPE B(1.8V)
1:TYPE A(2.5V)

APPLICABLE DIMM(REF.)



DETAIL A
(SCALE 5:1)
(REF. TABLE 1)



APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)

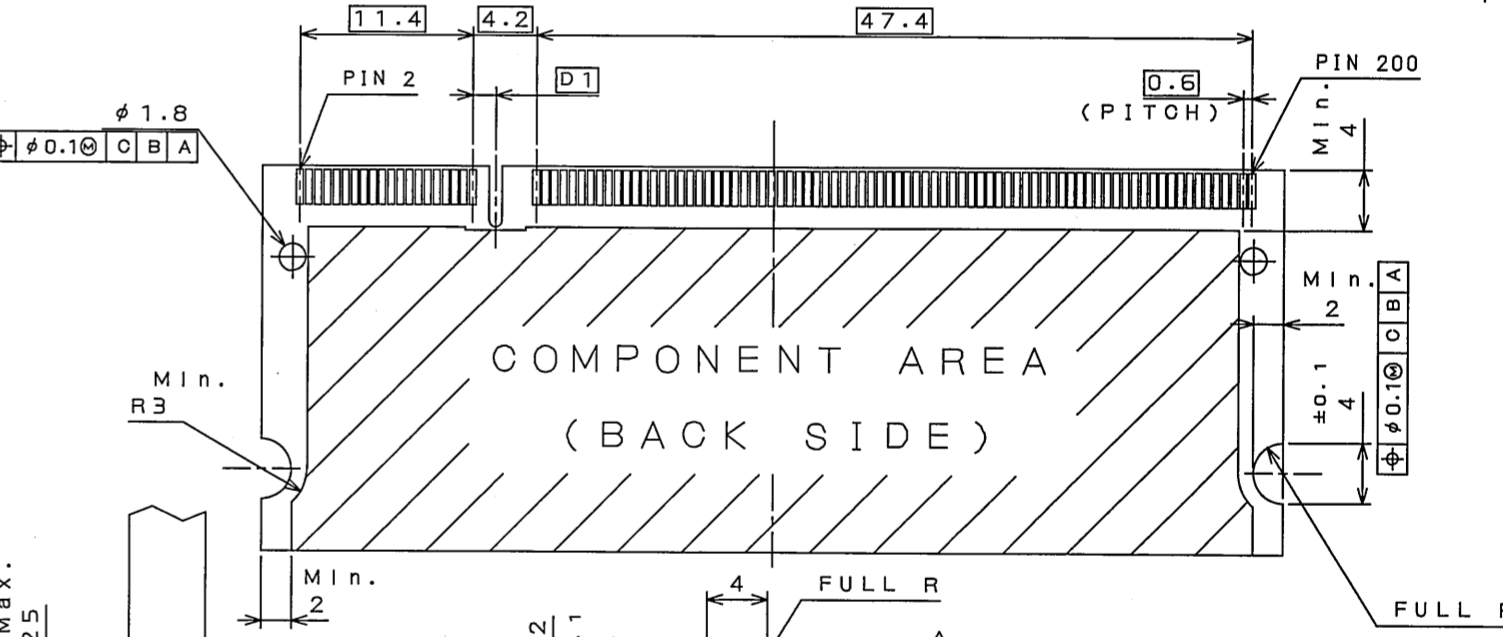
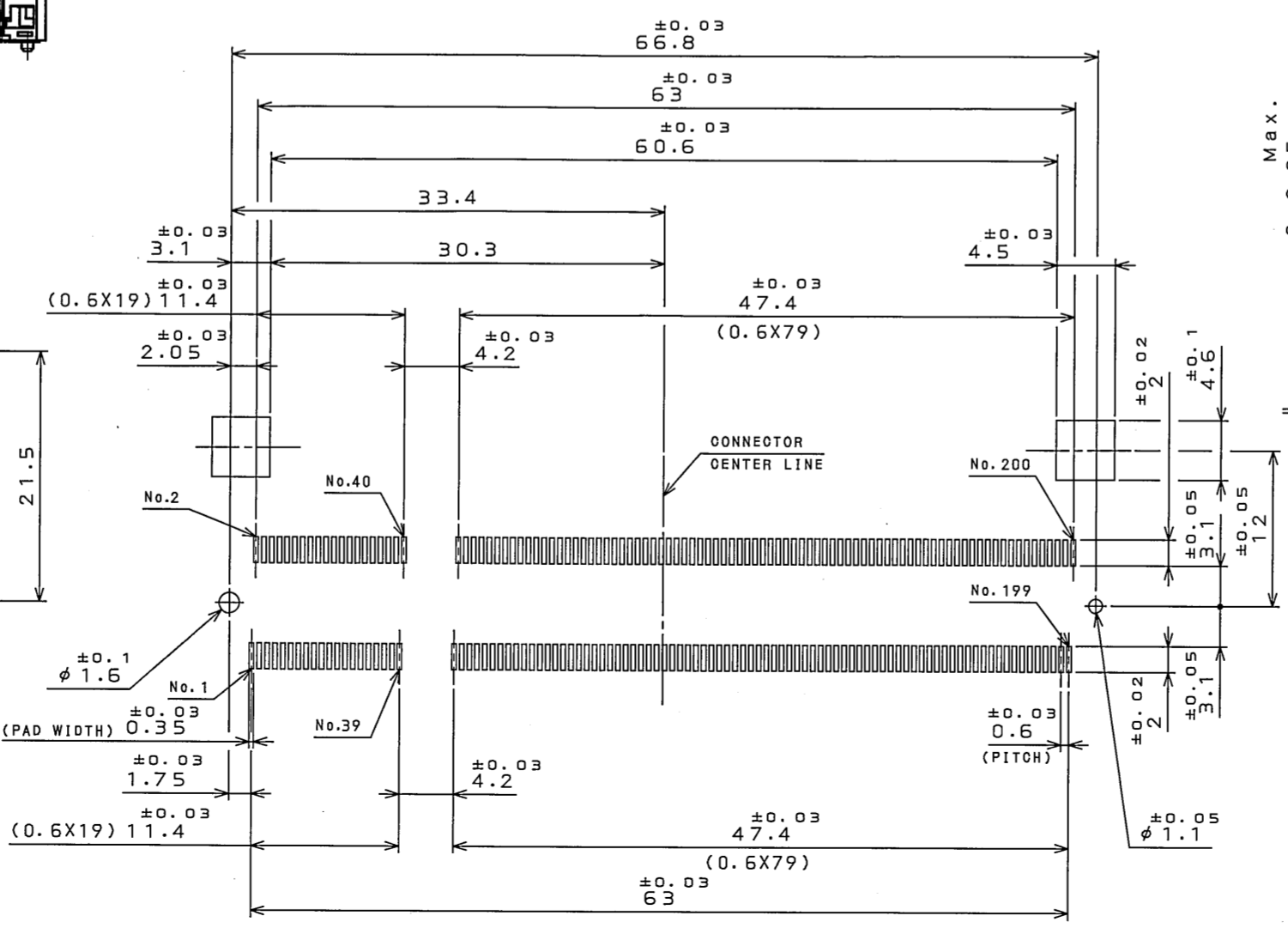
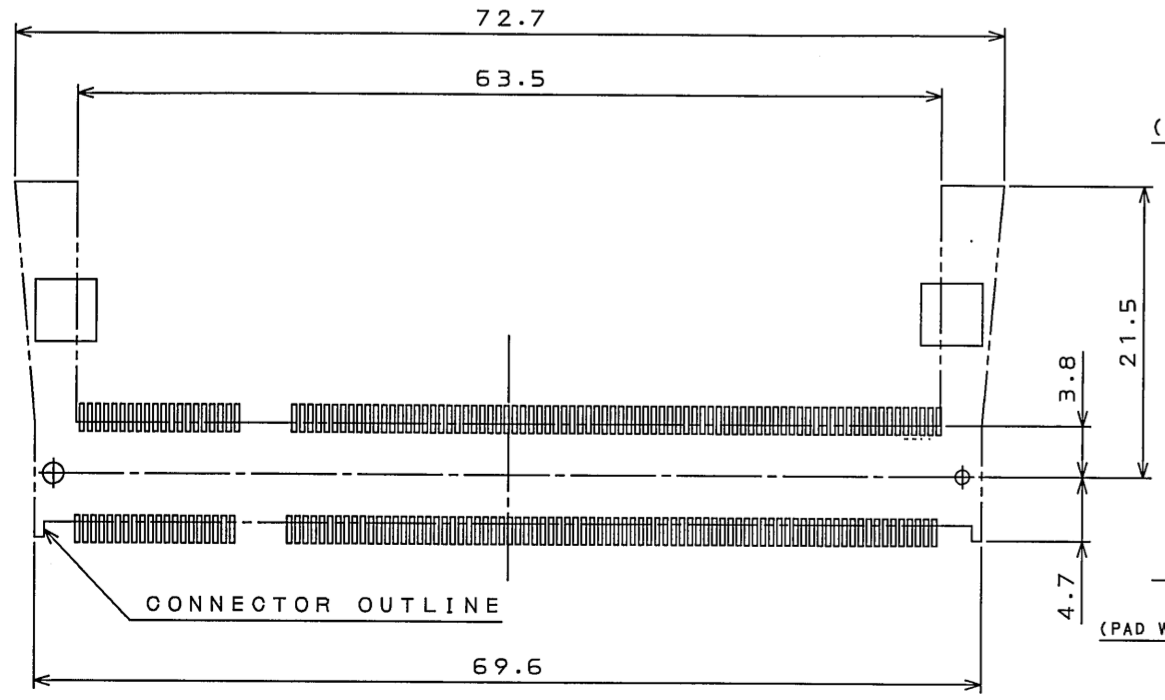
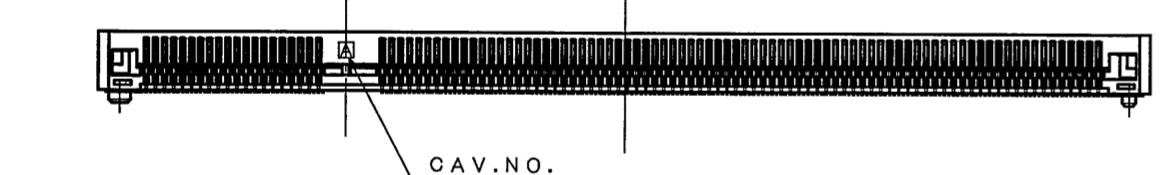
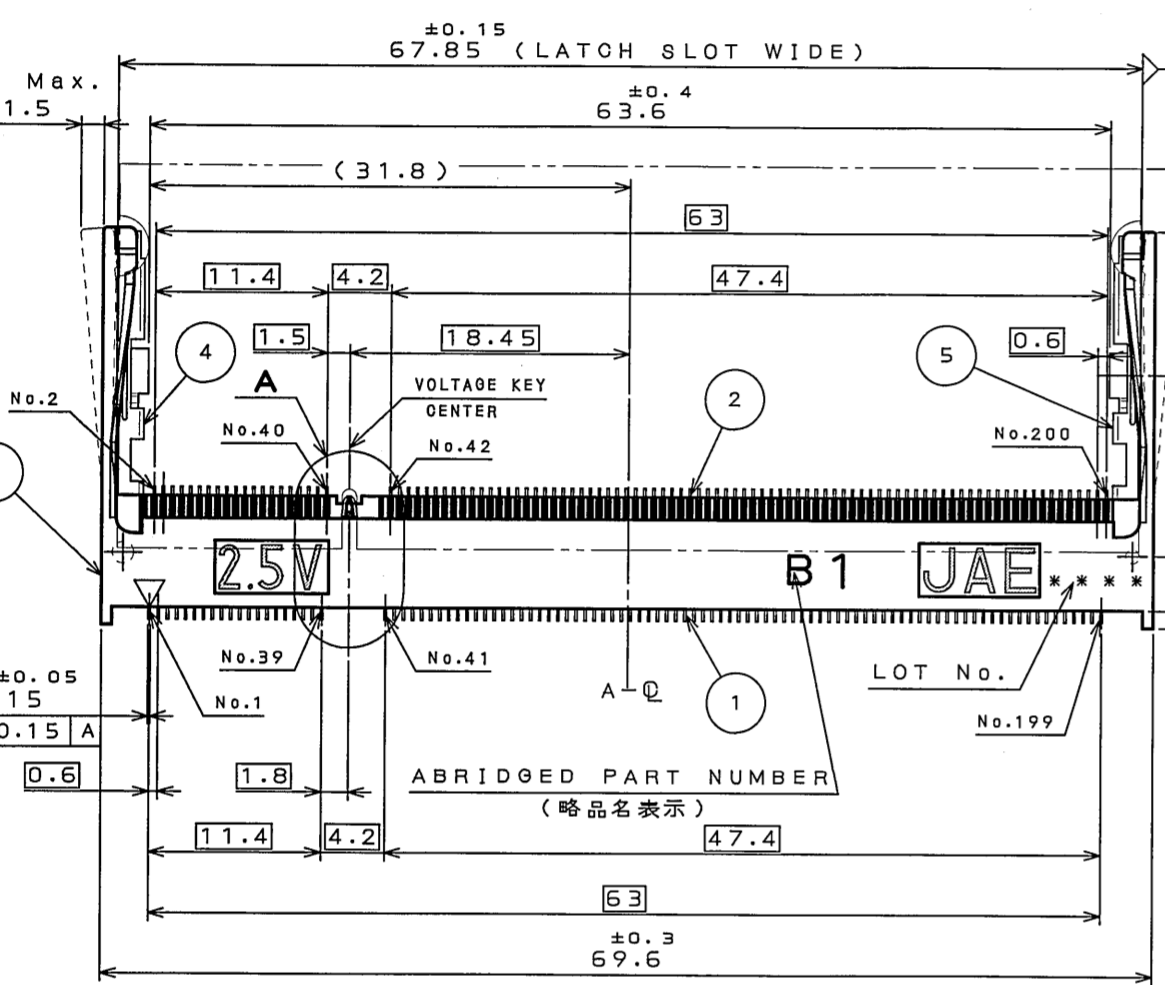
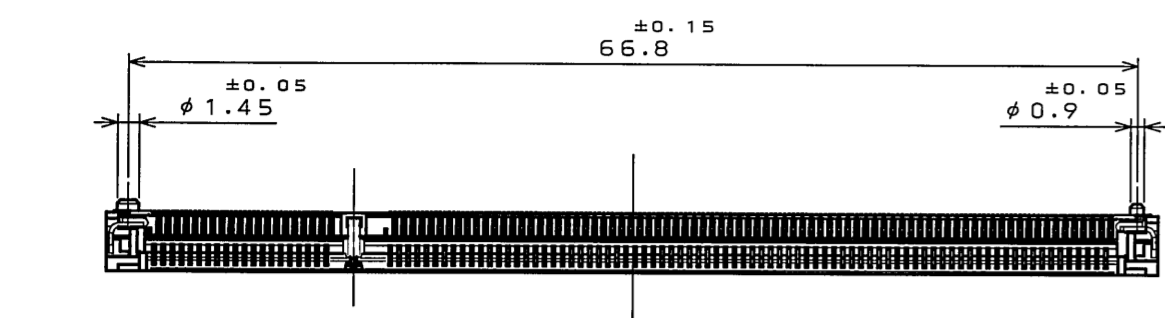


TABLE 1
MECHANICAL KEYING

POWER SPPLY	D1	D2	D3
2.5V(TYPE A)	1.5	1.8	18.45
1.8V(TYPE B)	2.4	2.7	17.55

DETAIL C

6 KEY	1 STAINLESS			
5 HOLD DOWN	2 1 PHOSPHOR BRONZE	TIN PLATING		
4 HOLD DOWN	1 1 PHOSPHOR BRONZE	TIN PLATING		
3 INSULATOR	1 GLASS FILLED LCP			
2 BOTTOM SIDE CONTACT	1 0 0 PHOSPHOR BRONZE	CONTACT AREA:Au(0.1µm MIN) OVER NI SOLDERING AREA:GOLD FLASH OVER NI		UL94 V-0 COLOR BLACK
1 TOP SIDE CONTACT	1 0 0 PHOSPHOR BRONZE	CONTACT AREA:Au(0.1µm MIN) OVER NI SOLDERING AREA:GOLD FLASH OVER NI		
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH
	JACS-1655-01			
仕様書(SPECIFICATION)	第1版(ORIGINAL DATE)	尺度(SCALE)	シリーズ(SERIES)	備考 REMARKS
	9.Aug.2002	2:1	MM50	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
公差(GENERAL TOLERANCE)	製図 DR.	名称(TITLE)		
寸法(DIMENSION) 角度(ANGLES)	担当 CHK. Y.YAHIRO	MM50 -200B*-B1		
. ±0.8 ° ±	査閲 APPD.			
.X ±0.4 °X° ±	承認 APPD. K.SUZUKI			
.XX ±0.1				
.XXX ±				
		質量(MASS)		図面番号(DRAWING NO.) SJ037105



DOF-0-213F(05.08)

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